

**Micro Commercial Components** 

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## ESDA6V1L

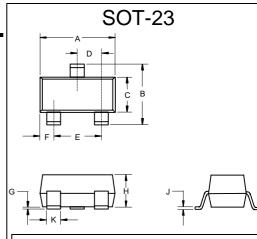
## **Features**

- Dual Transil Array For ESD Protection
- 2 Unidirectional Transil Functions
- Low leakageCurrent: IRmax<20 uA at Vwm</li>
- 300W peak pulse power (8/20 us)
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0and MSL rating 1

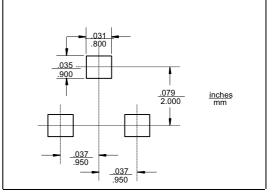
# 6.1Volts ESD Protection Device

# **Maximum Ratings**

Parameter	Symbol	Limits	unit
Electrostatic discharge MIL STD 883C-Method 3015-6 IEC61000-4-2 air discharge IEC61000-4-2 contact discharge	$V_PP$	25 16 9	KV KV KV
Peak pulse power 8/20us	P <sub>PP</sub>	300	W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature range	T <sub>stg</sub>	-55~+150	°C
Maximum lead temperature For soldering during 10s	$T_L$	260	°C



	INCHES		MM		
DIM	MIN	MAX	MIN	MAX	NOTE
Α	.110	.120	2.80	3.04	
В	.083	.098	2.10	2.64	
С	.047	.055	1.20	1.40	
D	.035	.041	.89	1.03	
Е	.070	.081	1.78	2.05	
F	.018	.024	.45	.60	
G	.0005	.0039	.013	.100	
Н	.035	.044	.89	1.12	
J	.003	.007	.085	.180	
K	.015	.020	.37	.51	



#### **Pin Configuration-Top View**

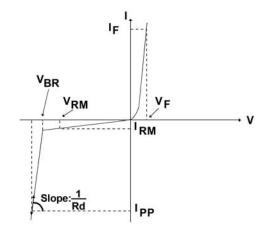


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#### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Symbol	Parameter	
$V_{WM}$	Stand-off voltage	
$V_{BR}$	Breakdown voltage	
$V_{CL}$	Clamping voltage	
I <sub>RM</sub>	Leakage current	
$I_{PP}$	Peak pulse current	
αΤ	Voltage temperature coefficient	
С	Capacitance	
$R_d$	Dynamic resistance	
$V_{F}$	Forward voltage drop	



Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Breakdown voltage	I <sub>R</sub> =1.0mA	$V_{BR}$	6.1	6.65	7.2	V
Leakage current	V <sub>WM</sub> =5.25V	I <sub>R</sub>	-	-	20	μΑ
Capacitance	0V bias	С	-	140	-	pF
Forward voltage drop	I <sub>F</sub> =200mA	V <sub>F</sub>	-	-	1.25	V



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#### TYPICAL CHARACTERISTICS

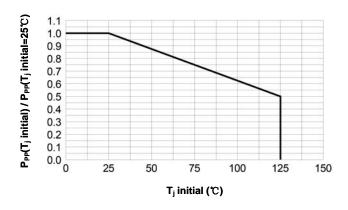


Fig.1: Peak power dissipation vs. initial junction temperature

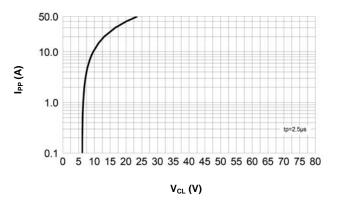


Fig.3: Clamping voltage vs. peak pulse current (Tj initial = 25°C, rectangular waveform tp = 2.5µs)

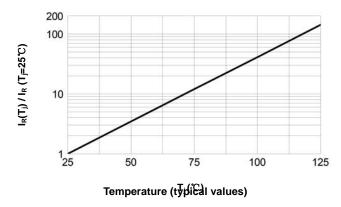


Fig.5: Relative variation of leakage current vs. junction

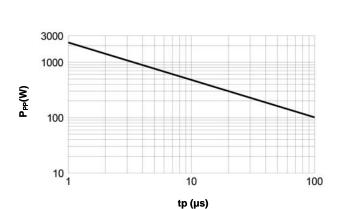


Fig.2: Peak pulse power vs. exponential pulse duration  $(T_j initial = 25 \degree)$ 

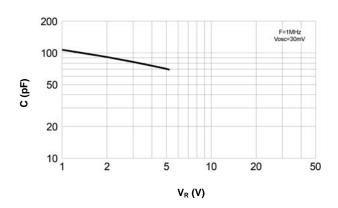


Fig.4: Capacitance vs. reverse applied voltage (typical values)

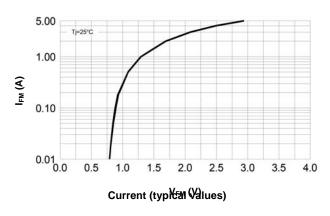


Fig.6: Peak forward voltage drop vs. peak forward



### **Ordering Information**

Device	Packing
(Part Number)-TP	Tape&Reel3Kpcs/Reel

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